



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Min-Lung HUANG Confirmation No: 8686  
Appl. No. : 10/820,856  
Filed : April 9, 2004  
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814  
Examiner : A. Kalam

Docket No.: : HUAN3261/REF  
Customer No: : 23364

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of October 29, 2007, in connection with the above-identified application. The period for response to this Official Action is set to expire on January 29, 2008. This response is timely filed.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.